



Dicing Peripherals | Wafer Handling Systems

955, 955L

UV Curing Systems



ADT UV Tape Curing Systems reduce the adhesive strength of all UV-sensitive dicing tapes under controlled environment.

Features & Benefits

- Intuitive control panel
- Enable time control process
- Compact design
- Compliance with the highest safety standards
- Environmentally friendly

	955 (8")	955L (12")
Max. frame diameter	300 mm	400 mm
Exposure area	250 x 250 mm	Ø430 mm
UV wavelength	365 nm	
Number of lamps	6	18
Machine dimensions (WxDxH)	510 x 450 x 120 mm	645 x 526 x 180 mm
Approx. machine weight	20 kg	35 kg

Options:

- Anti-ozone nitrogen diffusion kit
- Alarm buzzer
- Frame shutter

966, 966L

Manual Wafer Mounter



Designed for manual mounting of workpieces on tapes. This system accommodates a wide range of dicing tape varieties and standard frames. It can be tailored to suit diverse substrates (including multi-panel setups) and unconventional frame shapes.

Features & Benefits

Uniform tape tension and bubble-free mounting

- Temperature-controlled chuck heater
- Anti-static roller Reducing electrical charge
- Built-in vacuum holder
- UV back tape collector

	966	966L
Supported tapes	Dicing Blue-tapes / UV tapes	
Max. workpiece size	Ø 200 mm (8")	Ø 300 mm (12")
Supported film frames	DTF 2-8-1 ; DTF 2-6-1 350-103 ; 350-104	DTF-2-12 SEMI-G74
Temp Controlled Chuck heater	< 65°C	
Machine dimensions (WxDxH)	420 x 860 x 370 mm	550 x 1000 x 310mm
Approx. machine weight	45 kg	60 kg

Options:

- Electro-Static eliminator
- Plastic frame support
- Rectangular frame support
- Custom chucks and tailor made solutions